

<b>Notice of References Cited</b>	Application/Control No. 10/647,534		Applicant(s)/Patent Under Reexamination DIP ET AL.	
	Examiner Julio J. Maldonado		Art Unit 2823	Page 1 of 1

**U.S. PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
*	A	US-6,764,967 B2	07-2004	Pai et al.	438/787
*	B	US-6,613,677 B1	09-2003	Herbots et al.	438/694
*	C	US-6,194,327 B1	02-2001	Gonzalez et al.	438/770
	D	US-			
	E	US-			
	F	US-			
	G	US-			
	H	US-			
	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

**FOREIGN PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
	O					
	P					
	Q					
	R					
	S					
	T					

**NON-PATENT DOCUMENTS**

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Park et al., A study of modified silicon surface after CHF/sub3//C/cub2/F/sub6/ reactive ion etching, ETRI-Journal (south Korea, Vol.16, no.1, pages 45-47, April 1994.
	V	Wolf et al., Silicon Processing for the VLSI Era, Volume 1: Process Technology, 1986 by Lattice Press, pages 586-587 and 597-599.
	W	
	X	

\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.